Claims:

1. An electronics assembly which comprises:

(i) an enclosure;

(ii) a plurality of heat-generating components located within the enclosure that are provided with heat-sinks; and

(iii) one or more fans for providing a flow of air through the enclosure for cooling the components;

the components being located within the enclosure in line with the direction of the flow of air, and the heat-sinks having a configuration such that the air flows over the heat-sinks in parallel.

2. An assembly as claimed in claim 1, which includes two such heat-generating components.

3. An assembly as claimed in claim 1, wherein each heat-sink is mounted on one of the heat-generating components, and has a cantilevered portion that extends over the or one other of the heat-generating components but is not in contact therewith.

4. An assembly as claimed in claim 1, wherein each

heat-sink has a plurality of cooling fins.

5. An assembly as claimed in claim 4, wherein the components are mounted on a generally planar circuit board, and the fins are oriented generally perpendicular to the plane of the circuit board.

6. An assembly as claimed in claim 3, wherein each heat-sink has a plurality of cooling fins that are located on the cantilevered portion.

7. An assembly as claimed in claim 3, wherein each cantilevered portion extends over up to one half the transverse dimension of its associated heat-generating component in the direction of air flow.

8. An assembly as claimed in claim 2, wherein each heat-sink has a generally flat base that is mounted on its associated heat-generating component, a cantilevered portion that is provided with cooling fins and which extends over up to one half of the transverse dimension of its associated heat-generating component in the direction of air flow, the cantilevered portion of each heat-sink extending over the base of the other heat-sink,

and having a lower surface that is sufficiently higher than the upper surface of the base to allow clearance between the cantilevered portion and the base of the other heat-sink.

9. An assembly as claimed in claim 2, wherein the heat-sinks are substantially identical, and each heat-sink is oriented at 180° with respect to the other heat-sink.

10. An assembly as claimed in claim 1, wherein each heat-generating component generates substantially the same quantity of heat as the other component.

11. An assembly as claimed in claim 1, wherein each heat-generating component is a microprocessor.

12. An assembly as claimed in claim 1, wherein the enclosure has a generally flat shape to allow it to be stacked with one or more other such enclosures while allowing access to one or more side walls thereof.

13. An assembly as claimed in claim 12, which is a rack-mounted assembly.

14. An assembly as claimed in claim 1, which is a network server.

15. A method of cooling a plurality of heat-generating components in an electronics assembly, which comprises:

(i) providing a heat-sink on each of the heat-generating components; and

(ii) causing air to flow over the heat-sinks;

the components being located within the enclosure in line with the direction of the flow of air, and the heat-sinks having a configuration such that the air flows over the heat-sinks in parallel.

16. A method as claimed in claim 15, wherein the components are mounted on a generally planar circuit board, and air is caused to flow over the heat-sinks in a direction generally parallel to the plane of the circuit board.

17. A heat-sink for allowing cooling of a heat-generating electronics component, which comprises:

(i) a generally flat base for mounting on the component; and

(ii) a cantilevered portion having one end that is

located on, and supported by, the base and another end that extends beyond the base, the cantilevered portion having a plurality of fins extending therealong to allow forced-air cooling of the heat-sink;

wherein the cantilevered portion extends over not more than one half of the base in a direction transverse to its length.

18. A heat-sink as claimed in claim 17, wherein the cantilevered portion has a lower edge that is higher than the upper surface of the base.